Appl. No. 10/815,400 Amdt. dated June 6, 2006 Reply to Office Action of March 1, 2006

Amendments to the Specification:

Please replace the paragraph at lines 5-17 on page 10 with the following replacement paragraph:

Figure 2A is a side view of the present invention, showing a spring contact element 24 coupled to a substrate 26 at one end and having a tip structure 20 coupled thereto at an opposite end. Figure 2B is a pictorial illustration of the tip structure 20 of the present invention, having a blade 22 on the upper surface of the tip structure 20. In this embodiment of the present invention, the blade 22 comprises a contact element whose faces when extended form a line in space. When the tip structure 20 is placed in contact with a terminal $\frac{44}{2}$ of an electronic component (not shown) $\frac{42}{2}$ and a force $\frac{1}{2}$ is applied, the tip structure 20 will deflect across the surface of the terminal $\frac{44}{2}$. As the tip structure 20 deflects across the terminal $\frac{44}{2}$, the blade 22 of the tip structure 20 will penetrate the non-conductive layer on the surface of the terminal $\frac{44}{2}$. Figure 2C is a side view of the present invention. The dashed lines of Figure 2C show the interconnection element 24 and tip structure 22 after the deflection across the terminal $\frac{44}{2}$. ΔX represents the amount of lateral (or horizontal) deflection of the tip structure 20.